Components marked 'DNP' should not be populated.

Assembly Variant: 001

PCB Viewed from Top Side

Layer Name = M5 Assembly Top

Plot Name = Top Assembly Drawing

Board #: TIDA-01583

Rev: E1

Sun Rev: Not In VersionControl

TID #: TIDA-01583

Generated: 11/7/2017 10:49:21 PM

Texas Instruments
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01583</th>
<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = M6 Assembly Bottom</td>
<td>TID #: TIDA-01583</td>
<td></td>
<td></td>
</tr>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 11/7/2017 10:49:22 PM</td>
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<td>TEXAS INSTRUMENTS</td>
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</tbody>
</table>
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